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N. Chapman
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Application Serial No. 09/148,723
Filing Date September 3, 1998
Inventor Warren M. Farnworth et al.
Assignee Micron Technology, Inc.
Group Art Unit 3729
Examiner D. Tugbang
Attorney's Docket No. MI22-981
Title: Methods of Bonding Solder Balls To Bond Pads on a Substrate

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

References- - See attached Form PTO-1449

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the references listed on the attached Form PTO-1449. No admission is made regarding whether the submitted references are prior art.

Citation of these references is respectfully requested.

RECEIVED

AUG 26 2002

Respectfully submitted,

TECHNOLOGY CENTER R3700

Date: Aug. 19, 2002

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